# AOS Semiconductor Product Reliability Report 

## AOZ59141DI ${ }_{\text {rev }}$

Plastic Encapsulated Device

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The AOS product reliability report summarizes the qualification results for AOZ59141DI in DFN2x2-8L package. Accelerated environmental tests are performed on a specific sample size, samples are electrically tested before and after each stress time point. Review of final electrical test results confirm that AOZ59141DI pass the AOS quality and reliability requirements. The released products will be categorized by its process family and routinely monitored for continuous improvement of product quality.

## I. Reliability Stress Test Summary and Results

| Test Item | Test Condition | Time Point | Sample Size / Lots | Number of Failures | Reference Standard |
| :---: | :---: | :---: | :---: | :---: | :---: |
| HTOL | $\begin{aligned} & \mathrm{T}_{\mathrm{J}}=125^{\circ} \mathrm{C}, \\ & \mathrm{~V}_{\mathrm{cc}}=5.5 \mathrm{~V} \end{aligned}$ | $\begin{aligned} & 168 / 500 / \\ & 1000 \text { hours } \end{aligned}$ | 231 pcs <br> (3 lots) | 0 | JESD22-A108 |
| Preconditioning (Note A) | $\mathrm{T}_{\mathrm{A}}=85^{\circ} \mathrm{C}, \mathrm{RH}=85 \%+$ 3 cycle reflow @ $260^{\circ} \mathrm{C}$ (MSL 1) | 168 hours | 924 pcs <br> (3 lots) | 0 | JESD22-A113 |
| HAST | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=130^{\circ} \mathrm{C}, \mathrm{RH}=85 \%, \\ \mathrm{P}=33.3 \mathrm{psia}, \\ \mathrm{Vcc}=5.5 \mathrm{~V} \end{gathered}$ | 96 hours | 231 pcs (3 lots) | 0 | JESD22-A110 |
| Autoclave | $\begin{gathered} \mathrm{T}_{\mathrm{A}}=121^{\circ} \mathrm{C}, \mathrm{RH}=100 \%, \mathrm{P} \\ =29.7 \mathrm{psia} \end{gathered}$ | 96 hours | 231 pcs <br> (3 lots) | 0 | JESD22-A102 |
| Temperature Cycle | $\mathrm{T}_{\mathrm{A}}=-65^{\circ} \mathrm{C} \text { to } 150^{\circ} \mathrm{C},$ | $\begin{aligned} & 500 / 1000 \\ & \text { cycles } \end{aligned}$ | 231 pcs <br> (3 lots) | 0 | JESD22-A104 |
| HTSL | $\mathrm{T}_{\mathrm{A}}=150^{\circ} \mathrm{C}$ | 1000 hours | 231 pcs <br> (3 lots) | 0 | JESD22-A103 |
| Validation | 3 cycle reflow @ $260^{\circ} \mathrm{C}$ + 250 cycles @ $T_{A}=-65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$ | 250 cycles | $\begin{gathered} 3000 \\ (3 \text { lots }) \end{gathered}$ | 0 | AOS Standard |

Note: The reliability data presents total of available generic data up to the published date.
Note A: MSL (Moisture Sensitivity Level) 1 based on J-STD-020

## II. Reliability Evaluation

The presentation of FIT rate for the individual product reliability is restricted by the actual burn-in sample size of the product technology. Failure Rate Determination is based on JEDEC Standard JESD 85.

FIT rate (failures per billion device hours): 5.048
MTTF = 198.1 million hrs
Condition: $\mathrm{V}_{0}=5.5 \mathrm{~V}, \mathrm{~T}_{0}=55^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{s}}=5.5 \mathrm{~V}$ and $\mathrm{T}_{\mathrm{s}}=125^{\circ} \mathrm{C}$
Sample Size: Driver IC = 8,669
The failure rate $(\lambda)$ is calculated as follows:
$\lambda=\chi^{2}[C L,(2 f+2)] / 2 \times[1 /(S S \times t \times A F)] ;[e q u a t i o n ~ 1] \quad$ where

$$
\begin{aligned}
& C L=\% \text { of confidence level } \\
& \mathrm{f}=\text { number of failure } \\
& \mathrm{SS}=\text { sample size } \\
& \mathrm{t}=\text { stress time }
\end{aligned}
$$

Looking up the $\chi^{2} / 2$ table for zero failure (burn-in) with $60 \%$ confidence, the value of $\chi^{2}[C L,(2 f+2)] / 2$ is 0.92 .
The Acceleration Factor (AF) is calculated from the following formula (both temperature and voltage acceleration factors are used in the final acceleration factor calculation) :

$$
\mathrm{AF}=\mathrm{AF}_{\mathrm{T}} \times \mathrm{AFv}=\exp \left[\left(\mathrm{E}_{\mathrm{a}} / \mathrm{k}\right) \times\left(1 / \mathrm{T}_{0}-1 / \mathrm{T}_{\mathrm{s}}\right)\right] \times \exp [\beta(\mathrm{Vs}-\mathrm{Vo})] \text { where } \quad \begin{aligned}
& \mathrm{E}_{\mathrm{a}}=\text { activation energy } \\
& \mathrm{k}=\text { Boltzmann constant } \\
& \mathrm{T}_{0}=\text { operating } \mathrm{T}_{\mathrm{J}} \\
& \mathrm{~T}_{\mathrm{s}}=\text { stress } \mathrm{T}_{\mathrm{J}} \\
& \mathrm{~V}_{\mathrm{s}}=\text { stress voltage } \\
& \\
& \mathrm{V}_{0}=\text { operating voltage }
\end{aligned}
$$

Assuming typical operating environment, $\mathrm{V}_{\mathrm{o}}=5.5 \mathrm{~V}, \mathrm{~T}_{\mathrm{o}}=55^{\circ} \mathrm{C}, \mathrm{E}_{\mathrm{a}}=0.7 \mathrm{eV}, \mathrm{V}_{\mathrm{s}}=5.5 \mathrm{~V}$ and $\mathrm{T}_{\mathrm{s}}=125^{\circ} \mathrm{C}$

$$
A F=\exp \left[\left(\frac{0.7}{8.617 E-5}\right) \cdot\left(\frac{1}{273+55}-\frac{1}{273+125}\right)\right]
$$

Substituting the values in equation 1, we have
$0.92 \bullet \frac{1}{\text { sample Size } \bullet \text { Stress Duration } \bullet A F(\text { DriverIC })} h r^{-1}$
$\lambda=5.04810^{-9} \mathrm{hr}^{-1}$ or 5.048 FIT; MTTF $=(1 / \lambda)=198.1$ million hrs $=22,614$ years
The calculation shows failure rate is 5.048 FIT, MTTF is 198.1 million hours under typical operating conditions.

## III. ESD and Latch Up Test Results

| Test | Test Conditions | Total Sample <br> Size | Number of <br> Failures | Reference <br> Standard |
| :---: | :---: | :---: | :---: | :---: |
| Electrostatic Discharge <br> Human Body Model | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C},+/-2 \mathrm{kV}$ | 10 | 0 | JESD-A114 |
| Electrostatic Discharge <br> Charged Device Model | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C},+/-1 \mathrm{kV}$ | 10 | 0 | JESD-C101 |
| Latch Up | $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, <br> $+/-100 \mathrm{~mA}, 1.5 \mathrm{x}$ OV | 10 | 0 | JESD78 |
| Latch Up | $\mathrm{T}_{\mathrm{A}}=125^{\circ} \mathrm{C}$, <br> $+/-100 \mathrm{~mA}, 1.5 \mathrm{x}$ OV | 10 | 0 | JESD78 |

Note: ATE results are used to determine PASS/FAIL. Parametric shift<10\%.


DFN2x2-8L
(Top View)

